

STRUCTURE  
PRODUCTSERIES

Silicon Monolithic Integrated Circuit  
2-ch Switching Regulator Controller

TYPE

**BD9848FV**

FEATURES

- High Input-voltage (  $V_{CC}=35V$  )
- MOSFET-driver circuit built-in ( dual circuit for step-down output )
- Built-in circuits for error amplifier reference voltage (  $1.0V \pm 1\%$  )
- 5 consecutive over current pulse detection circuit built in.
- Soft-start timing adjustable
- Master/Slave function

○Absolute maximum ratings (  $T_a=25^\circ C$  )

Item	Symbol	Limits	Unit
Power Supply Voltage	$V_{CC}$	36	V
Power dissipation	$P_d$	812 <sup>*1</sup>	mW
Output pin voltage	$V_{OUT}$	$V_{CC}-7V \sim V_{CC}$	V
C5V pin voltage	$V_{C5V}$	$V_{CC}-7V \sim V_{CC}$	V
Operating temperature	$T_{opr}$	$-40 \sim +105$	$^\circ C$
Storage temperature	$T_{stg}$	$-55 \sim +150$	$^\circ C$
Maximum Junction temperature	$T_{jmax}$	150	$^\circ C$

<sup>\*1</sup> Should be deleted by  $6.5mW/^\circ C$  at  $T_a=25^\circ C$  or more. When mounted on a glass epoxy PCB of  $70.0mm \times 70.0mm \times 1.6mm$

○Recommended operating range (  $T_a=25^\circ C$  )

Item	Symbol	Min.	Typ.	Max.	Unit
Power Supply Voltage	$V_{CC}$	3.6	6.0	35	V
Output pin voltage	$V_{OUT}$	C5V	-	$V_{CC}$	V
Error amplifier input voltage	INV	0	-	$V_{REF}-0.9$	V
Timing capacitor	$C_{CT}$	47	-	3000	pF
Oscillation frequency	$f_{osc}$	100	-	1500	kHz
STB input voltage	$V_{STB}$	0	-	$V_{CC}$	V
DT input voltage	DT	0	-	$V_{REF}+0.3$	V
OCP+/- input voltage	$V_{OCP}$	$V_{CC}-0.2$	-	$V_{CC}+0.2$	V
CExternal oscillation waveform input voltage range	$V_{ctH}$	1.9	-	$2.3 < V_{REF}$	V
	$V_{ctL}$	1.4	-	$1.6 < V_{REF}$	V

○Electrical characteristics (Unless otherwise specified,  $T_a=25^\circ C$ ,  $V_{CC}=6V$ )

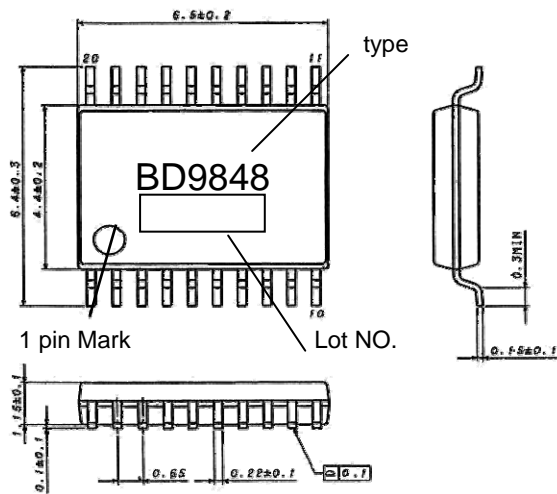
Item	Symbol	Limits			Unit	Conditions
		Min.	Typ.	Max.		
【VREF output block】						
VREF output voltage	VREF	2.475	2.500	2.525	V	Io=0.1mA
Line regulation	Line reg.	—	1	10	mV	Vcc=3.6V→35V
Load regulation	Load reg.	—	2	10	mV	Io=0.1mA→2mA
Output max. current	IOMAX	2	13	—	mA	VREF=(typ.) * 0.95

○Electrical characteristics (Unless otherwise specified, Ta=25°C, VCC=6V)

Item	Symbol	limits			Unit	Conditions
		Min.	Typ.	Max.		
【Triangular wave oscillator block】						
Oscillation frequency	fOSC	95	106	117	kHz	CCP=1800pF
Frequency variation	fDV	—	0	1	%	Vcc=3.6V→35V
【Soft-start block】						
SS pin source current	ISSSO	1.4	2	2.6	μ A	SS=0.5V
SS pin sink current	ISSSI	5	12	—	mA	SS=0.5V
【Dead time adjustable circuit block】						
DT pin input bias current	IDT	—	0.1	1	μ A	DT=1.75V
DT pin sink current	IDTSI	1	3.3	—	mA	DT=1.75V, (OCP+)-(OCP-)=0.5V
【UVLO block】						
Threshold voltage	VUTH	3.0	3.2	3.4	V	Vcc when rise time
Hysterisis	VUHYS	—	0.15	0.25	V	
【Error Amp block】						
Non-Inverting input reference	VINV	0.99	1	1.01	V	INV=FB
Reference voltage variation	dVinv	—	1	6	mV	Vcc=3.6V→35V
INV input bias current	IIB	—	0	1	μ A	INV=1V
Open loop gain	AV	70	85	—	dB	
Output FB voltage (Hi)	VFBH	2.30	—	VREF	V	
Output FB voltage (Low)	VFBL	—	0.6	1.3	V	
Output sink current	IFBSI	0.5	1.5	—	mA	FB=1.25V , INV=1.5V
Output source current	IFBSO	50	105	—	μ A	FB=1.25V , INV=0V
【PWM comparator】						
Input threshold voltage (fosc=100kHz)	Vt0	1.4	1.5	1.6	V	On duty 0%
	Vt100	1.9	2	2.1	V	On duty 100%
【Output block】						
Output ON resistance H	RONH	—	4	10	Ω	RONH=( Vcc -OUT)/ Iout, Iout=0.1A
Output ON resistance L	RONL	—	3.3	10	Ω	RONL=(OUT-C5V)/ Iout, Iout=0.1A
C5V clamp voltage	VCLMP	4.5	5	5.5	V	VCLMP= Vcc-C5V , Vcc > 7V
【Over current protection circuit (OCP) block】						
OCP threshold voltage	VOCPTH	0.04	0.05	0.06	V	Voltage between (OCP+)-(OCP-)
OCP-input bias current	IOCP-	—	0.1	10	μ A	OCP+= Vcc, OCP-= Vcc-0.05V
Delay time for OCP	tdocpth	—	200	400	nS	OCP-= Vcc→Vcc-0.2V
Min. hold time for OCP	tdocpre	0.8	1.6	—	mS	OCP-= Vcc-0.2V→Vcc
【Stand-by switch block】						
Threshold voltage for each CH stop	VDThL	1.1	1.25	1.4	V	DT Pin H/L
Stand-by mode setting voltage range	VSTBL	0	—	0.5	V	
Slave mode setting voltage range	VSTBM	2.4	2.5	2.6	V	
Active(Master) mode setting voltage range	VSTBH	3	—	Vcc	V	
STB current	ISTB	—	70	100	μ A	STB=6V
【Total device】						
Stand-by current	ICCS	—	0	1	μ A	STB=0V
Average current consumption	ICCA	1.5	3	6	mA	INV=0V, FB=H, DT=1.75V

※Not designed for radiation resistance.

○Outline figure



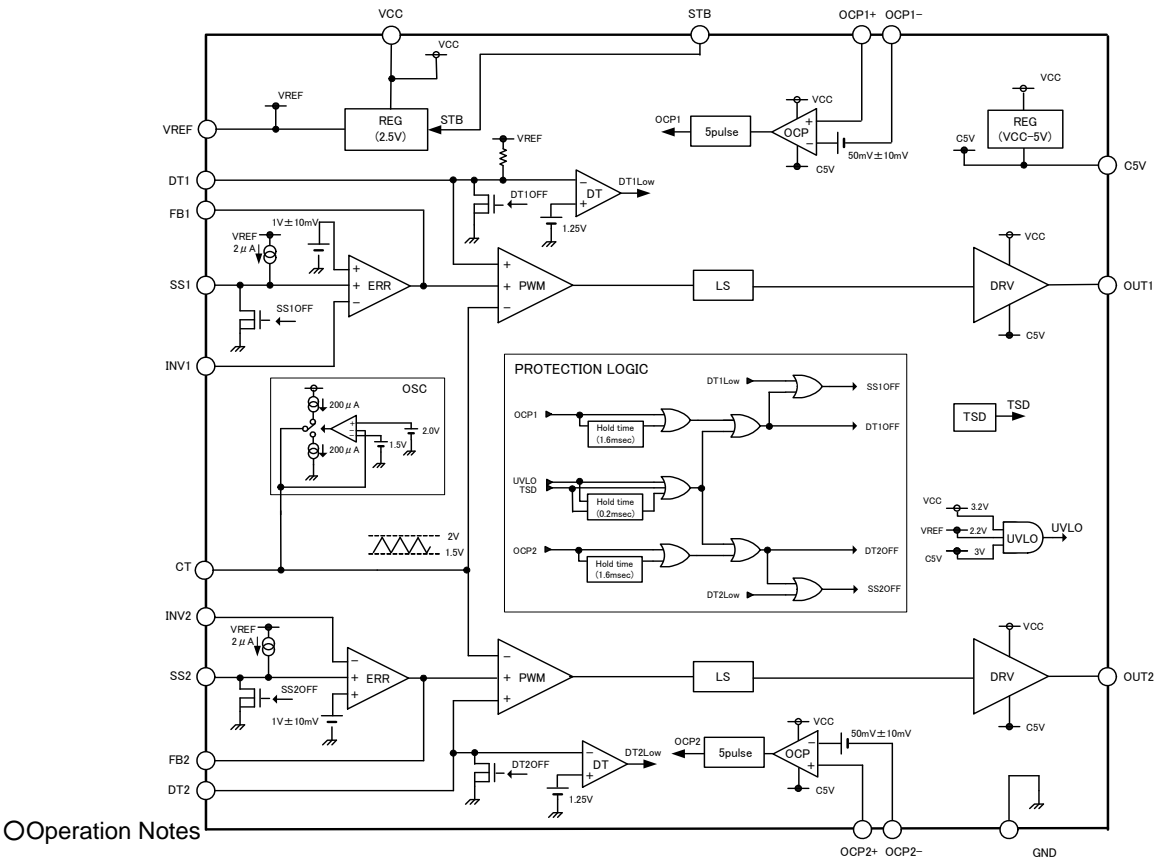
SSOP-B20 (Unit : mm)

○PIN No./ name / function

Pin No.	Pin name	Pin function
1	CT	External Capacitor pin for timing change
2	DT2	Dead time setting (CH2)
3	SS2	Soft-start time setting (CH2)
4	INV2	Error Amp inverting input (CH2)
5	FB2	Error Amp output (CH2)
6	GND	GROUND
7	OCP2-	Over current error amp inverting input (CH2) ※
8	OCP2+	Over current error amp input (CH2) ※
9	C5V	Output L voltage (Vcc-5V)
10	OUT2	CH2 Output
11	OUT1	CH1 Output
12	Vcc	Power supply input
13	OCP1+	Over current error amp input (CH1) ※
14	OCP1-	Over current error amp inverting input (CH1) ※
15	STB	Stand-by mode control
16	FB1	Error Amp output (CH1)
17	INV1	Error Amp inverting input (CH1)
18	SS1	Soft-start time setting (CH1)
19	DT1	Dead time setting (CH1)
20	VREF	Reference voltage (2.5V) output

○Block Diagram

※ Refer p.4 Operation note(9)



○Operation Notes

### 1) Absolute maximum ratings

Use of the IC in excess of absolute maximum ratings such as the applied voltage or operating temperature range may result in IC deterioration or damage. Assumptions should not be made regarding the state of the IC (short mode or open mode) when such damage is suffered. A physical safety measure such as a fuse should be implemented when use of the IC in a special mode where the absolute maximum ratings may be exceeded is anticipated.

### 2) GND potential

Ensure a minimum GND pin potential in all operating conditions. In addition, ensure that no pins other than the GND pin carry a voltage lower than or equal to the GND pin, including during actual transient phenomena.

### 3) Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

### 4) Inter-pin shorts and mounting errors

Use caution when orienting and positioning the IC for mounting on printed circuit boards. Improper mounting may result in damage to the IC. Shorts between output pins or between output pins and the power supply and GND pin caused by the presence of a foreign object may result in damage to the IC.

### 5) Operation in a strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

### 6) Thermal shutdown circuit (TSD circuit)

This IC incorporates a built-in thermal shutdown circuit (TSD circuit). The TSD circuit is designed only to shut the IC off to prevent runaway thermal operation. Do not continue to use the IC after operating this circuit or use the IC in an environment where the operation of the thermal shutdown circuit is assumed.

### 7) Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Ground the IC during assembly steps as an antistatic measure, and use similar caution when transporting or storing the IC. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process.

### 8) Common impedance

Power supply and ground wiring should reflect consideration of the need to lower common impedance and minimize ripple as much as possible (by making wiring as short and thick as possible or rejecting ripple by incorporating inductance and capacitance).

### 9) Over Current Protection

The OCP circuit is designed to be very sensitive circuit for protection of an application device. Therefore, it may detect ringing noises besides the true current signal. This depends on an application circuit and a layout pattern. In this case, the OCP current value is lower than the designed value. For the measure of this, please use CR filter on OCP input referring the circuit of the technical note.

### 10) General

Please refer the technical note on designing.

### 11) IC pin input

This monolithic IC contains P+ isolation and PCB layers between adjacent elements in order to keep them isolated.

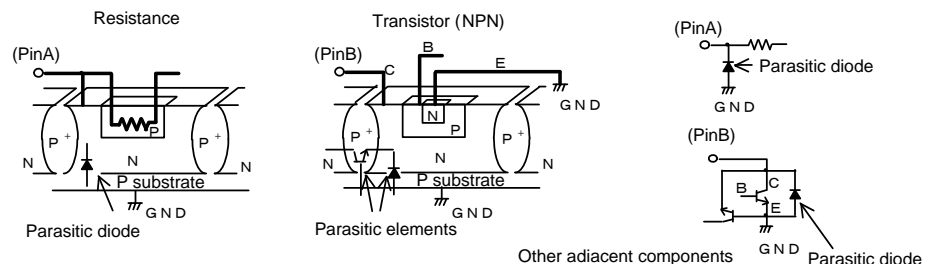
P/N junctions are formed at the intersection of these P layers with the N layers of other elements to create a variety of parasitic elements.

For example, when a resistor and transistor are connected to pins as shown in Fig. 10,

- The P/N junction functions as a parasitic diode when GND > (Pin A) for the resistor or GND > (Pin B) for the transistor (NPN).

- Similarly, when GND > (Pin B) for the transistor (NPN), the parasitic diode described above combines with the N layer of other adjacent elements to operate as a parasitic NPN transistor.

The formation of parasitic elements as a result of the relationships of the potentials of different pins is an inevitable result of the IC's architecture. The operation of parasitic elements can cause interference with circuit operation as well as IC malfunction and damage. For these reasons, it is necessary to use caution so that the IC is not used in a way that will trigger the operation of parasitic elements, such as by the application of voltages lower than the GND (PCB) voltage to input and output pins.



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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASS III	CLASS III	CLASS II b	CLASS III
CLASS IV		CLASS III	

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  - Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - Sealing or coating our Products with resin or other coating materials
  - Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - Use of the Products in places subject to dew condensation
- The Products are not subject to radiation-proof design.
- Please verify and confirm characteristics of the final or mounted products in using the Products.
- In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

## Precaution for Mounting / Circuit board design

- When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

## Precautions Regarding Application Examples and External Circuits

1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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## Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of ionizer, friction prevention and temperature / humidity control).

## Precaution for Storage / Transportation

1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
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2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
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